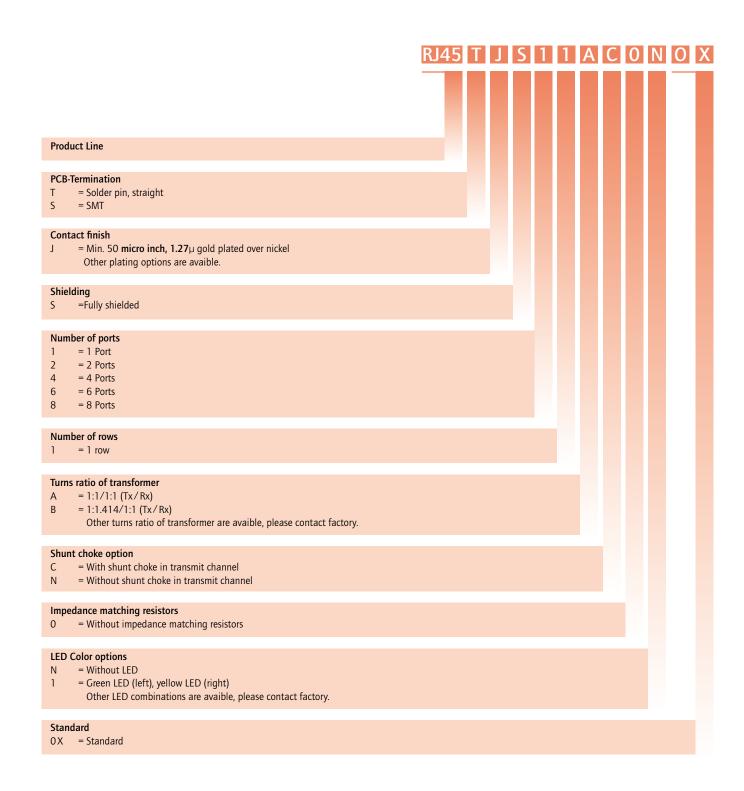
PART NUMBER CREATOR

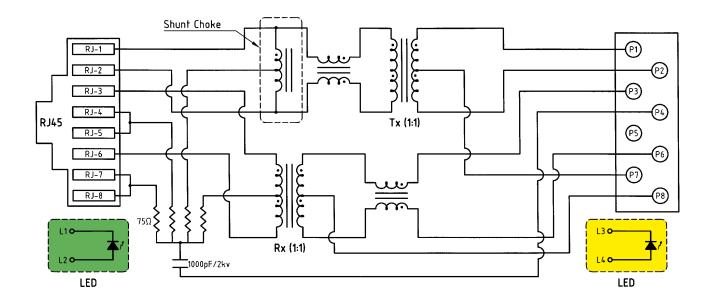


TECHNICAL DATA

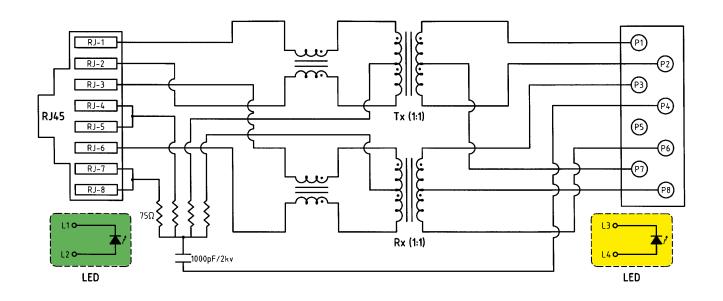
Specifications						
Housing, solder pin, straight	Polyester glass fille	Polyester glass filled, black, UL94 V-0				
Housing, SMT-Termination	Nylon 46 glass filled, black, UL94 V-0					
Shielding	.008"/0.20 mm thick copper alloy					
Contact material	.014"/0.35 mm thick copper alloy					
Mating area plating	50μ"/1.27 μm gold min. over 30μ"/0.76 μm min. nickel					
Solder tails plating	Tin plated					
OCL (Open Circuit Inductance)	Min. 350 µH at 8mA DC bias					
Leakage inductance	Max. 0.35 μH					
Inter-winding capacitance	Max. 25 pF					
DC-Resistance	Max. 1.0 Ω					
Turns ratio	$1:1/1:1 \pm 3\%$ or Tx/Rx = $1:1.414/1:1 \pm 3\%$					
Rise time and fall time	3.0 ns (typical)					
Mating force	Max. 22 N					
Retention force	Min. 89 N					
Mating cycles	Min. 1 000					
Contact resistance	Max. 20 mΩ					
Insulation resistance	Min. $1000 \text{ m}\Omega$					
Dielectric with standing voltage	1 500V ms (Signal to Shield)					
Current rating	Max. 0,05A					
Spezification at 25°C (Operating temperature -40°C to +85°C)						
Insertion loss	0.1-100 MHZ	1.0 dB max				
Return loss	0.1-30 MHZ	20.0 dB Type				
	60 MHZ	15.0 dB Type				
	80 MHZ	12.0 dB Type				
Next near and cross talk	0.1-30 MHZ	50.0 dB Type				
	60 MHZ	45.0 dB Type				
	100 MHZ	40.0 dB Type				
Biff (i.i.	COMUZ	40.0 ID.T				
Differential to common mode rejection	60 MHZ	40.0 dB Type				
	100 MHZ	35.0 dB Type				
Common mode rejection ration	60 MHZ	35.0 dB Type				
	100 MHZ	30.0 dB Type				
Hi-Pot	1500 Vrms	60 sec.				
Standard-LED						
Color	Green	Yellow				
w I d	FCF	FOF				
Wave length	565 nm	585 nm				
Forward voltage with I _F =20 mA	2.6 V (max)	2.6 V (max)				
	2.1 V (Type)	2.0 V (Type)				
Reserve voltage with I_R =10 μ A	5.0 V (Type)	5.0 V (Type)				
	0.0 . (1) [0]	(-)[]				
Luminous intensity with I _F =20 mA	15 mcd (min)	20 mcd (min)				
	25 mcd (Type)	30 mcd (Type)				
	23 med (Type)	30 maa (1)po)				

SCHEMATICS

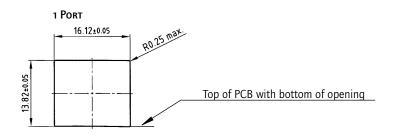
Schematic of magnetic Circuit with Tx/Rx = 1:1/1:1 or Tx/Rx = 1:1.414/1:1 - Turns Ratio, additional shount Chok, $4x0,75\Omega$ Terminal Resistors - 1000pF/2kv Capacitor and LEDs (Optional)

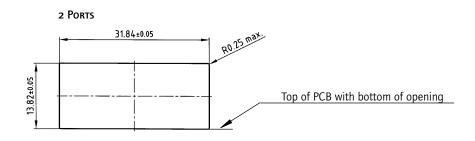


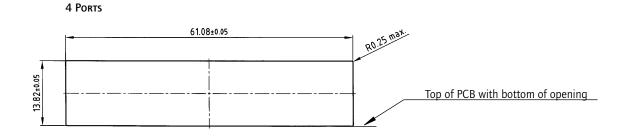
Schematic of magnetic Circuit with Tx/Rx = 1:1/1:1 or Tx/Rx = 1:1.414/1:1 - Turns Ratio, additional $4x0,75\Omega$ Terminal Resistors - 1000pF/2kv Capacitor and LEDs (Optional).

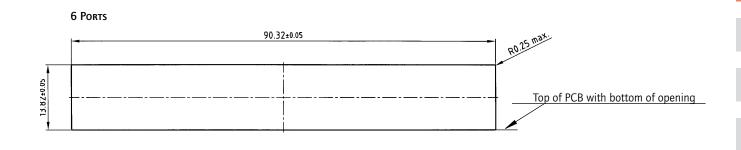


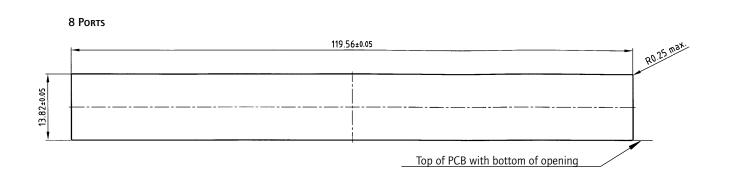
RECOMMENDED PANEL CUT-OUT





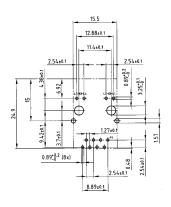




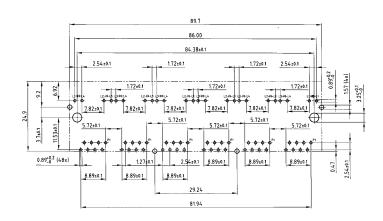


PCB LAYOUT FOR SOLDER PIN STRAIGHT

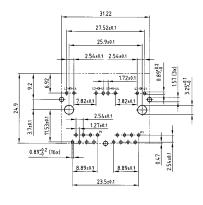
1 Port



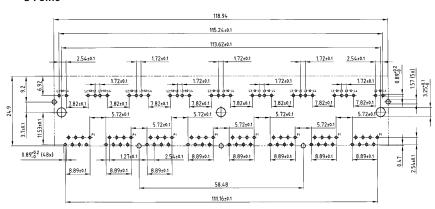
6 Ports



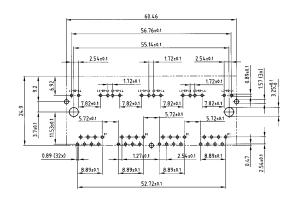
2 Ports



8 Ports



4 Ports

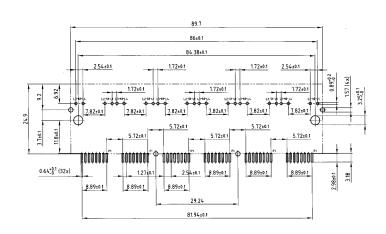


PCB LAYOUT FOR SMT-TERMINATION

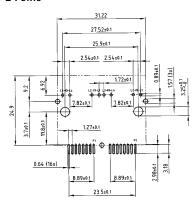
1 Port

15.5 12.88±0.1 0.64^{+0.1}₋₀ (8x) 3.18 1.27±0.1 8.89±0.1

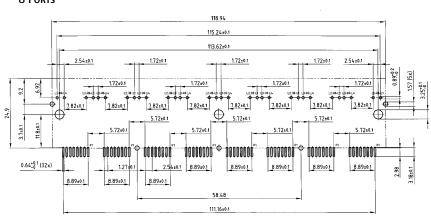
6 Ports



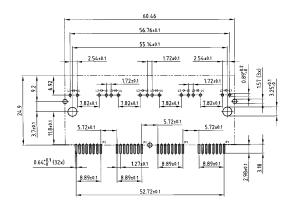
2 Ports



8 Ports



4 Ports



SOLDER PROFILE

Connector Type	Preheating		Solder terminal dipping parameters	
	max. Temperature	Duration	max. Solder bath Temperature	max. Terminal Immersion Time
Filter D-SUB	100°C	30s	260°C	5s
Combo D-SUB Filter	120°C	120s	260°C	5s
Filter D-SUB Water Resistant	100°C	30s	240°C	5s
Combo D-SUB Water Resistant	120°C	120s	240°C	5s
D-SUB Water Resistant	120°C	120s	240°C	5s
D-SUB Solid Body Type Water Resistant	150°C	180s	265°C	8s
RJ45 Modular Jack Filtered	150°C	180s	265°C	8s
Filter Plates	150°C	180s	265°C	8s

Recommended wave-solder parameters for CONEC connectors.